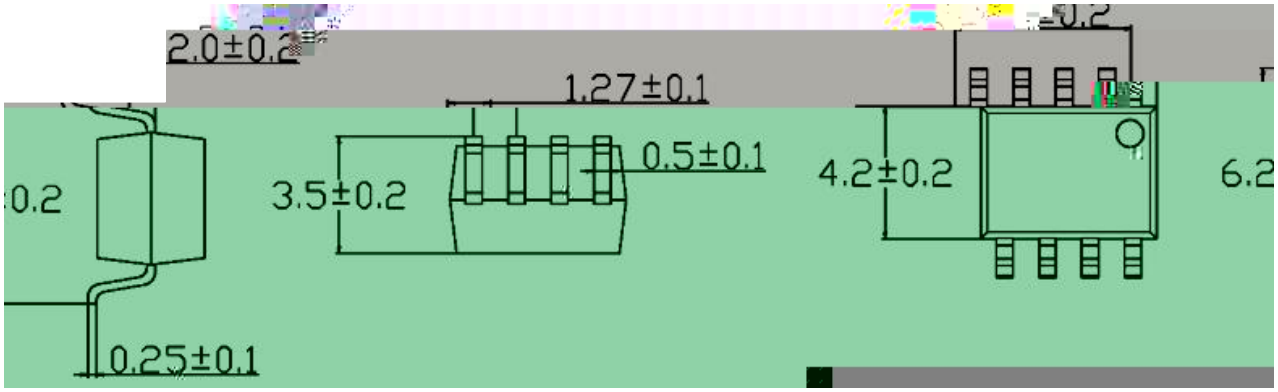
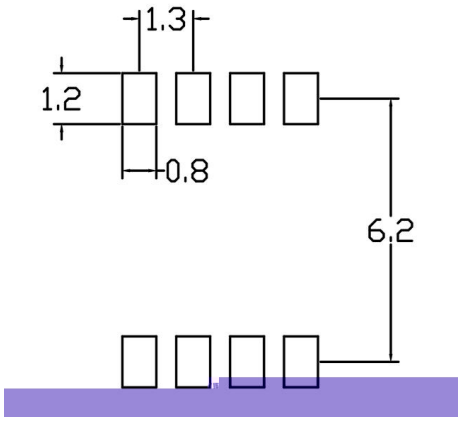

2.0±0.2
1.27±0.1
0.5±0.1
3.5±0.2
4.2±0.2
0.25±0.1


1.3
1.2
0.8
6.2

| | | | | |
|---|---|---|---|---|
| Preheat temperayure | Ts | 150 | 200 | |
| Preheat time | ts | 60 | | s |
| Ramp-up ratea($T_L$ to $T_P$) | | | | /s |
| Liquidus temperature | T | | 217 | |
| Time above | $t_L$ | 60 | | s |
| Peak temperature | Tp | | | |
| Time during which Tc between ($T_P$-5) and $T_P$ | $t_p$ | | | s |
| Ramp-down rate to $T_L$ | | | | |

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.